

ABSTRACT

A method for removing hard material layers from hard metal substrates by employing a layer removal solution, included introducing between the hard metal substrate and a hard material layer, an intermediate carrier layer made of a material that is differing from the material of the hard material layer and from the metal substrate. A selectively dissolving of the intermediate carrier layer follows by employing a solution such as hydrogen peroxide, through pores of the hard material layer. The removal solution, within a treatment time period, dissolves the material of the intermediate carrier layer more than the material of the hard material layer, such that the hard material layer is removed before it is dissolved as much as the intermediate carrier layer.

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